



PART NO. : TG110-EX50J2LF

16PIN SMT ISOLATION MODULE FOR 10/100BASE-TX
IEEE802.3u APPLICATIONS

LEAD-FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS

CONDITION PER IPC/JEDEC J-STD-020C

OPERATING TEMPERATURE -55/+125°C

ELECTRICAL SPECIFICATIONS @25°C

TURNS RATIO

P1-3:P16-14

1CT:1CT ±3%

P6-8:P11-9

1CT:1CT ±3%

OCL (100KHz,0.1Vrms,8mADC)

P1-3,P6-8

350μH min

120μH min (-55/+125°C)

DCR P9-11,P14-16

0.9Ω max

LL P1-3,P6-8

0.4μH max

Cw/w

35pF max

INSERTION LOSS

0.1-100MHz

-1.1dB max

RETURN LOSS

0.5-30MHz

-18dB min

40MHz

-15.5dB min

50MHz

-13.6dB min

60-80MHz

-12dB min

CROSSTALK 0.1-100MHz

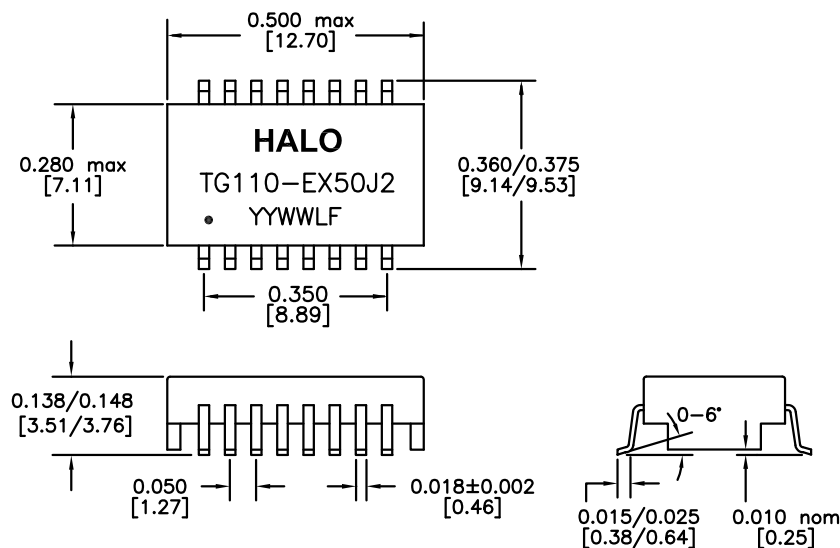
-40dB typ

CMR 0.1-100MHz

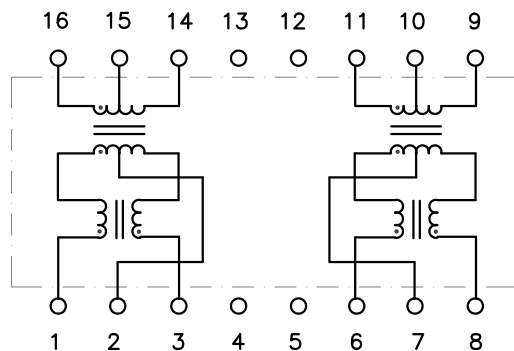
-40dB typ

ISOLATION

1,500Vrms



DIMENSIONS: Inch[mm]
CO-PLANARITY: 0.004[0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE TRANSFORMER "ULTRA" SERIES

FOR FAST ETHERNET

PART NO. TG110-EX50J2LF

SCALE NONE

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SIGNATURES

DRAWN LI ZHI ZHONG

CHECKED LEI KEONG

APPROVED PETER LU

FILE EX50J2LF.DWG

DATE

12/21/15

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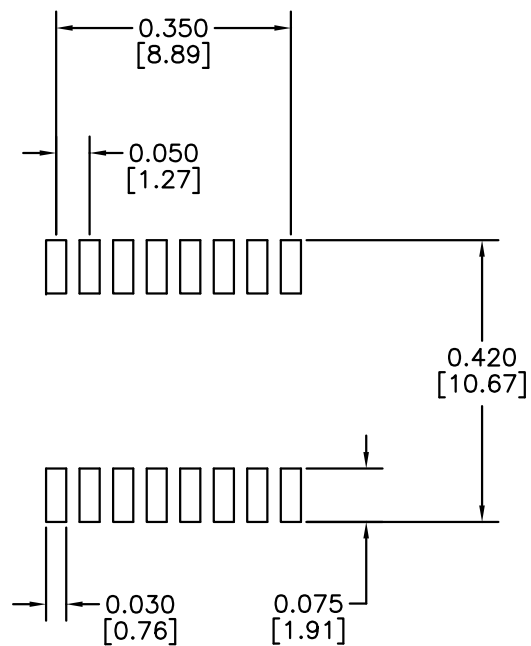
REV.

A

DESC.

PROD. RELEASE





RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL

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